JOC307XD5 Series

Rev.A.1.1

DESCRIPTION:

The JOC307XD5 series combine an AIGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac in a plastic DIP5 package with different lead forming options. With the robust coplanar double mold structure, JOC307XD5 series provide the most stable isolation feature. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors up to 265 V_{AC} peripherals.

MAIN FEATURES

High isolation 5000 VRMS

DC input with random-phase photo triac output

Operating temperature range -

	Junction Temperature	T_j	125	
	Output Power Dissipation	P_O	250	

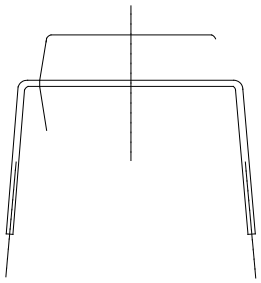
JOC307XD5

FIG.7: Normalized On-state Terminal Voltage vs. Ambient Temperature

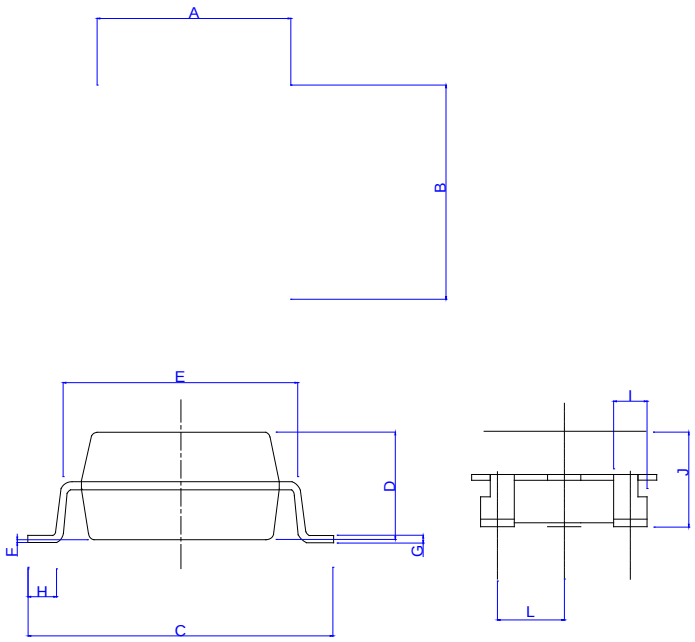
FIG.8: On-state Terminal Voltage vs. On-state Terminal Current

Package Dimension (Unit: mm

Standard DIP Type:

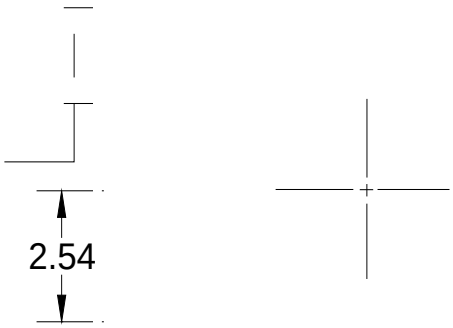


Option SLM Type:



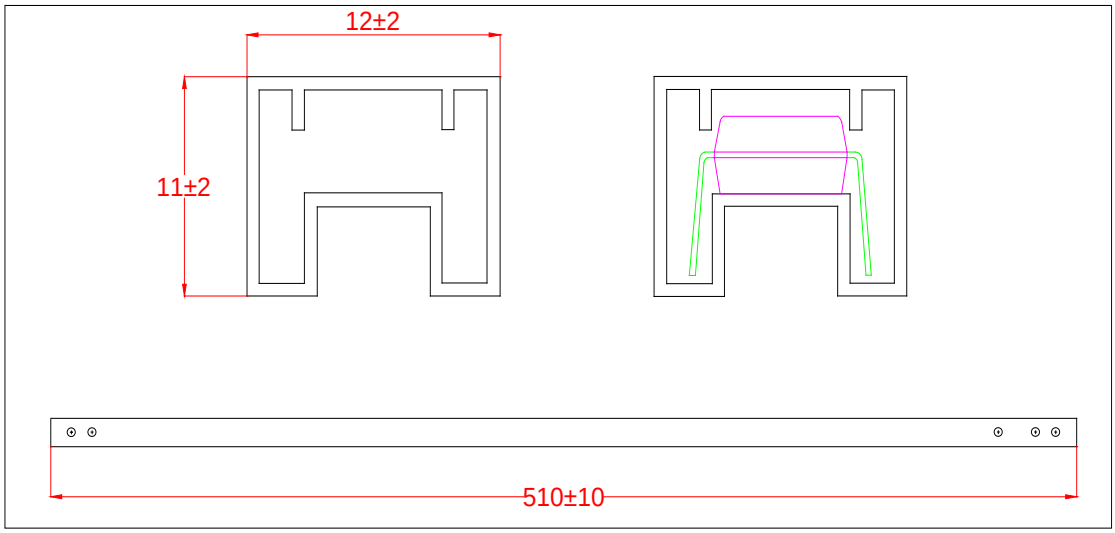
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30		6.70	0.248		0.264
B	6.92		7.32	0.272		0.288
C	11.60		12.10	0.457		0.476
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.288		0.312
F			0.30			0.012
G						
H	0.50			0.020		
I	1.10		1.30	0.043		0.051
J	3.45		3.85	0.136		0.152
K						

Option SL

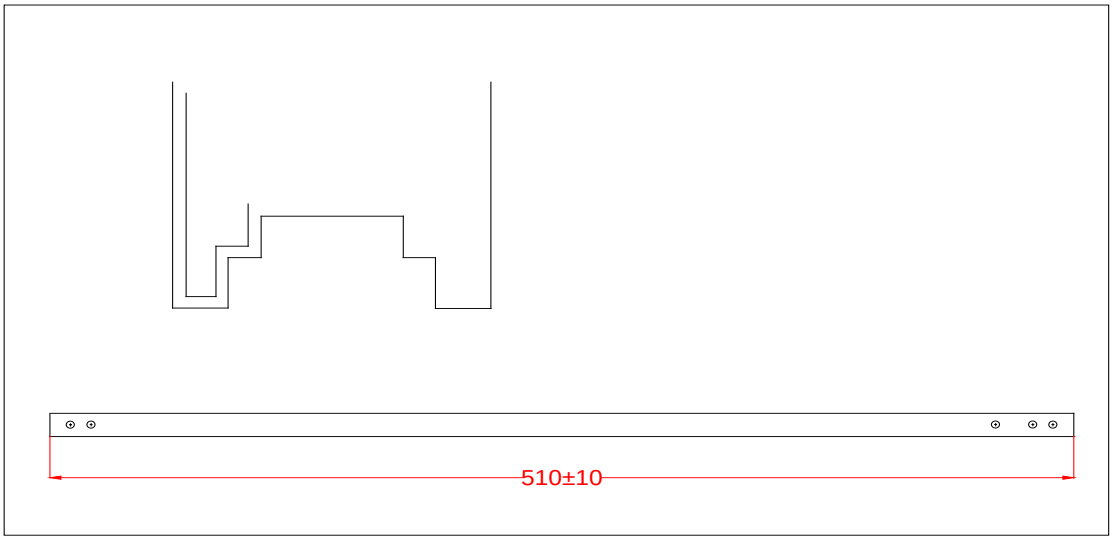


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

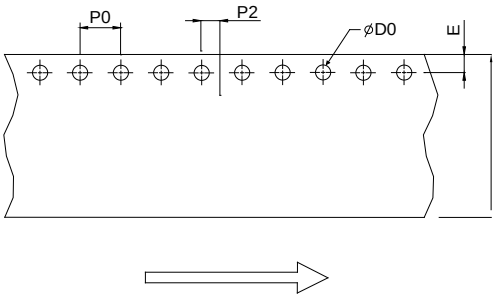
Standard DIP



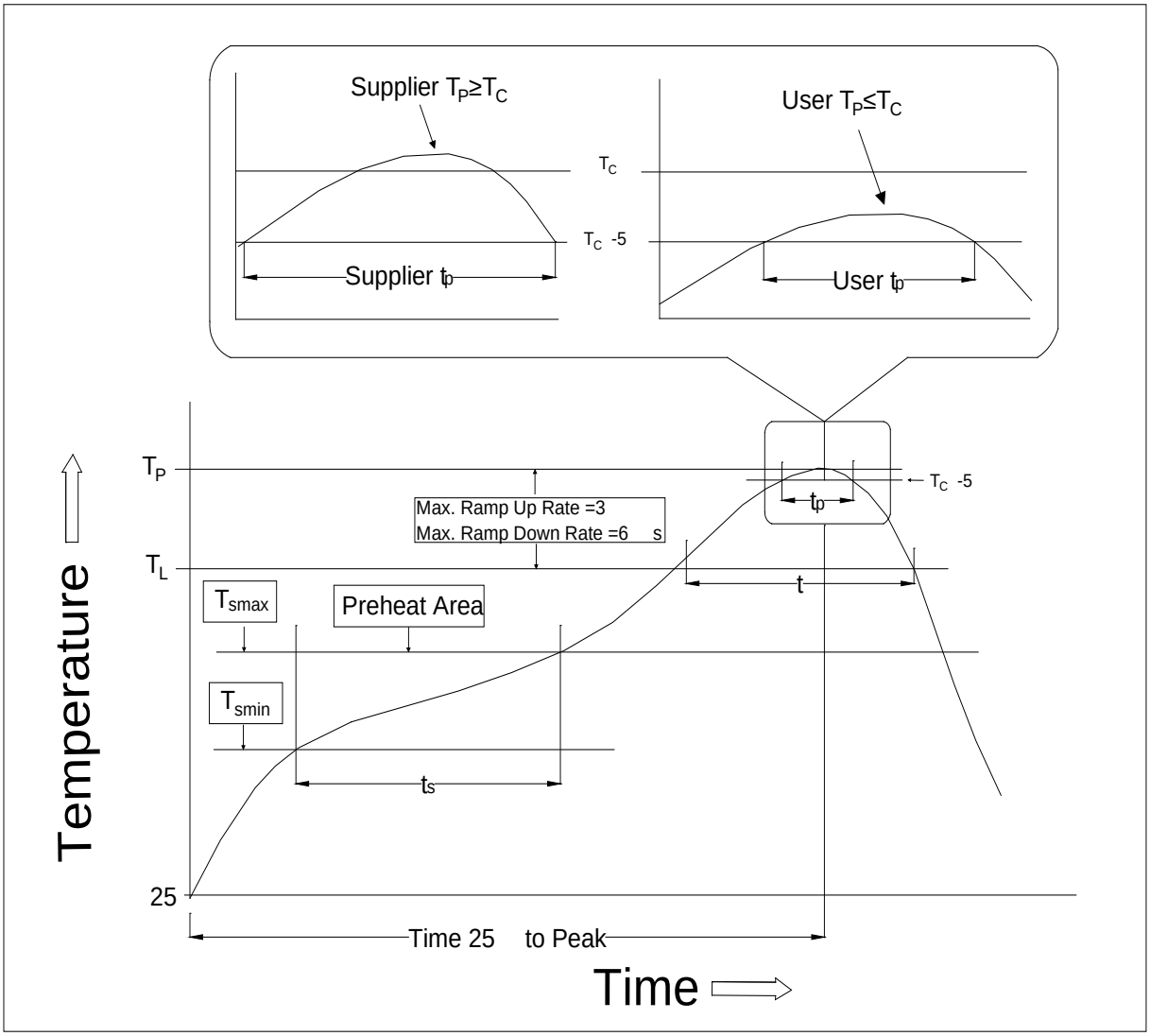
Option M



CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated) EQ0064502 0 0 -0

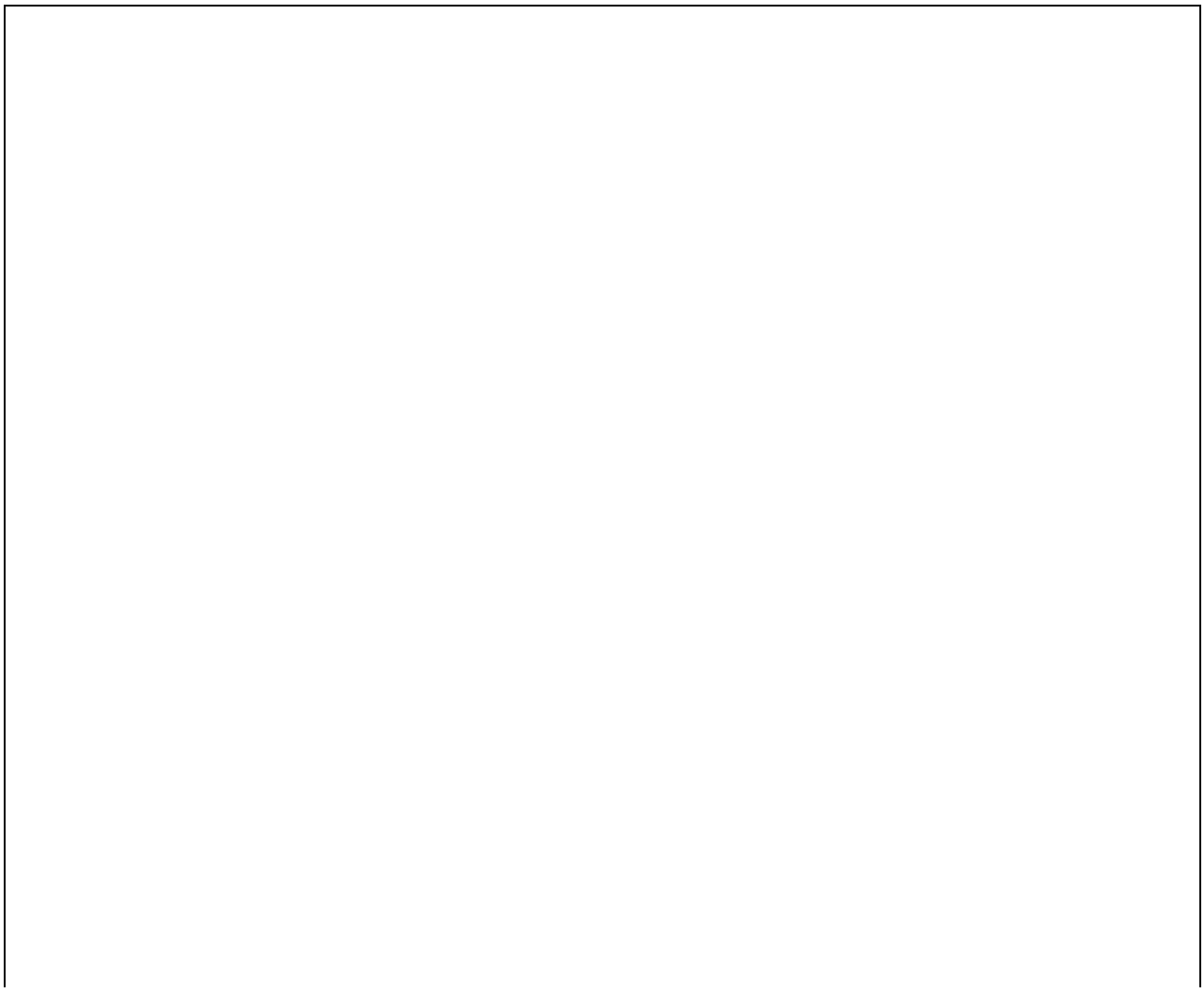


REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6 /second max.	6 /second max.
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



Document Revision History

Date	Revision	Changes
Apr.2, 2025	A.1.0	Last update
Nov.5, 2025	A.1.1	Add S&SLM package

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